



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



MC12026A

1.1 GHz Dual Modulus Prescaler

Description

The MC12026A is a high frequency, low voltage dual modulus prescaler used in phase-locked loop (PLL) applications.

The MC12026A can be used with CMOS synthesizers requiring positive edges to trigger internal counters in a PLL to provide tuning signals up to 1.1 GHz in programmable frequency steps.

A Divide Ratio Control (SW) permits selection of an 8/9 or 16/17 divide ratio as desired.

The Modulus Control (MC) selects the proper divide number after SW has been biased to select the desired divide ratio.

Features

- 1.1 GHz Toggle Frequency
- Supply Voltage 4.5 to 5.5 V
- Low Power 4.0 mA Typical
- Operating Temperature Range of -40 to 85°C
- The MC12026 is Pin Compatible with the MC12022
- Short Setup Time (t_{set}) 6.0 ns Typical @ 1.1 GHz
- Modulus Control Input Level is Compatible with Standard CMOS and TTL
- These Devices are Pb-Free, Halogen Free and are RoHS Compliant

Table 1. FUNCTIONAL TABLE

SW	MC	Divide Ratio
H	H	8
H	L	9
L	H	16
L	L	17

1. SW: H = V_{CC} , L = Open. A logic L can also be applied by grounding this pin, but this is not recommended due to increased power consumption.
2. MC: H = 2.0 V to V_{CC} , L = GND to 0.8 V.

Table 2. MAXIMUM RATINGS

Characteristics	Symbol	Value	Unit
Power Supply Voltage, Pin 2	V_{CC}	-0.5 to 7.0	Vdc
Operating Temperature Range	T_{A}	-40 to 85	$^{\circ}\text{C}$
Storage Temperature Range	T_{stg}	-65 to 150	$^{\circ}\text{C}$
Modulus Control Input, Pin 6	MC	-0.5 to 6.5	Vdc
Maximum Output Current, Pin 4	I_{O}	10.0	mA

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

NOTE: ESD data available upon request.



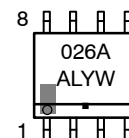
ON SemiconductorTM

www.onsemi.com



**SOIC-8 NB
D SUFFIX
CASE
751-07**

MARKING DIAGRAM*

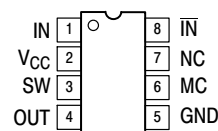


- A = Assembly Location
- L = Wafer Lot
- Y = Year
- W = Work Week
- = Pb-Free Package

(Note: Microdot may be in either location)

*For additional marking information, refer to Application Note [AND8002/D](#).

PIN CONNECTIONS



(Top View)

ORDERING INFORMATION

Device	Package	Shipping [†]
MC12026ADG	SOIC-8 NB (Pb-Free)	98 Units/Tube
MC12026ADR2G	SOIC-8 NB (Pb-Free)	2500/Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, [BRD8011/D](#).

MC12026A

Table 3. ELECTRICAL CHARACTERISTICS ($V_{CC} = 4.5$ to 5.5 ; $T_A = -40$ to 85°C , unless otherwise noted.)

Characteristic	Symbol	Min	Typ	Max	Unit
Toggle Frequency (Sin Wave)	f_t	0.1	1.4	1.1	GHz
Supply Current Output Unloaded (Pin 2)	I_{CC}	-	4.0	5.3	mA
Modulus Control Input High (MC)	V_{IH1}	2.0	-	V_{CC}	V
Modulus Control Input Low (MC)	V_{IL1}	GND	-	0.8	V
Divide Ratio Control Input High (SW)	V_{IH2}	$V_{CC} - 0.5$ V	V_{CC}	$V_{CC} + 0.5$ V	V
Divide Ratio Control Input Low (SW)	V_{IL2}	OPEN	OPEN	OPEN	-
Output Voltage Swing ($R_L = 560 \Omega$; $I_O = 5.5$ mA) (Note 1) ($R_L = 1.1$ k Ω ; $I_O = 2.9$ mA) (Note 2)	V_{out}	1.0	1.6	-	V_{pp}
Modulus Setup Time MC to Out (Note 3)	t_{SET}	-	6.0	9.0	ns
Input Voltage Sensitivity 100–250 MHz 250–1100 MHz	V_{in}	400 100	- -	1000 1000	mVpp

1. Divide Ratio of +8/9 at 1.1 GHz, $C_L = 8.0$ pF.
2. Divide Ratio of +16/17 at 1.1 GHz, $C_L = 8.0$ pF.
3. Assuming $R_L = 560 \Omega$ at 1.1 GHz.

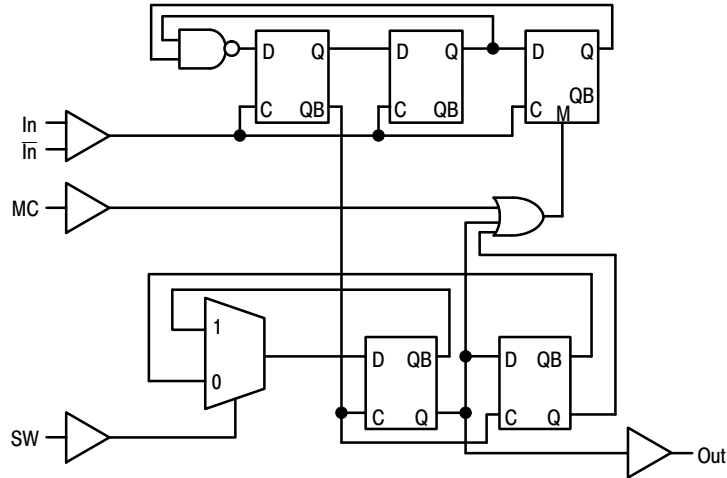
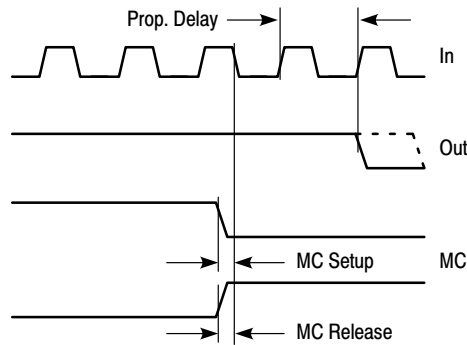


Figure 1. Logic Diagram (MC12026A)



Modulus setup time MC to out is the MC setup or MC release plus the prop delay.

Figure 2. Modulus Setup Time

MC12026A

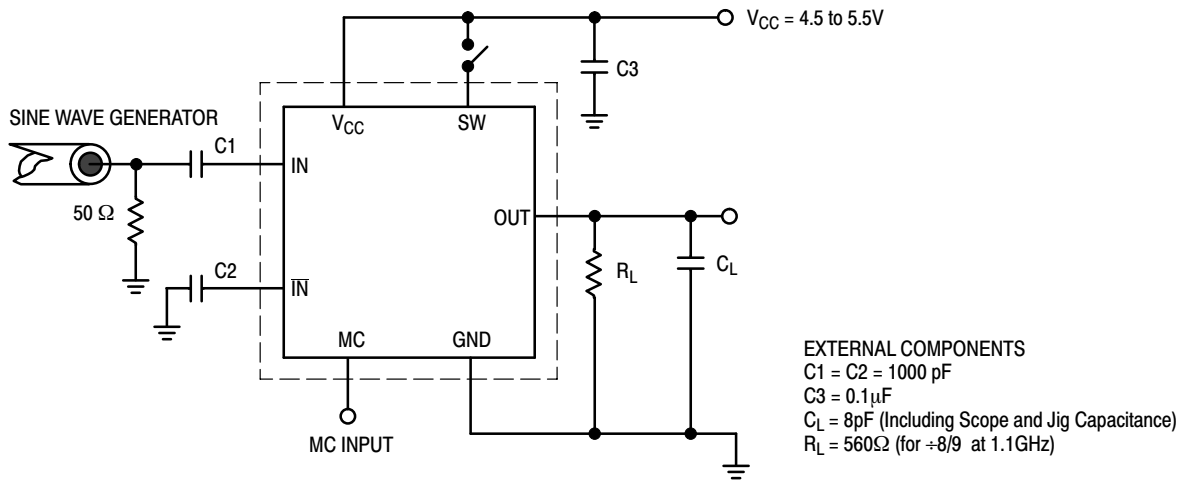
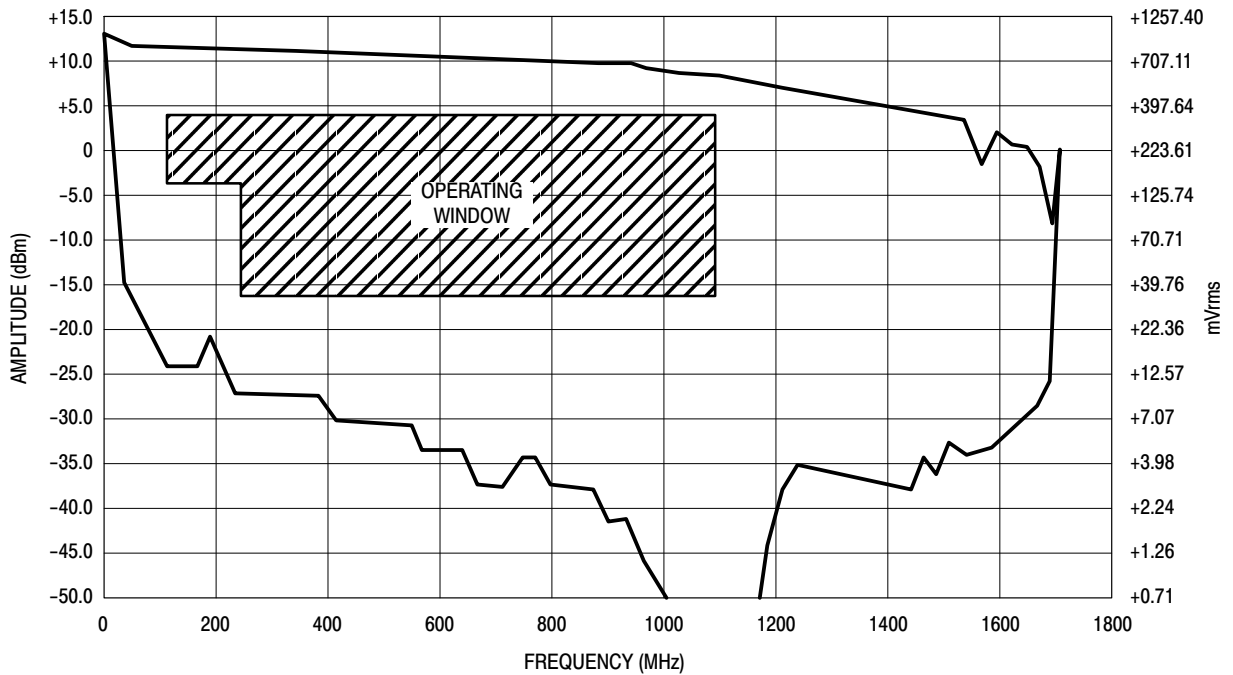


Figure 3. AC Test Circuit



Divide Ratio = 8; V_{CC} = 5.0 V; T_A = 25°C

Figure 4. Input Signal Amplitude Versus Input Frequency

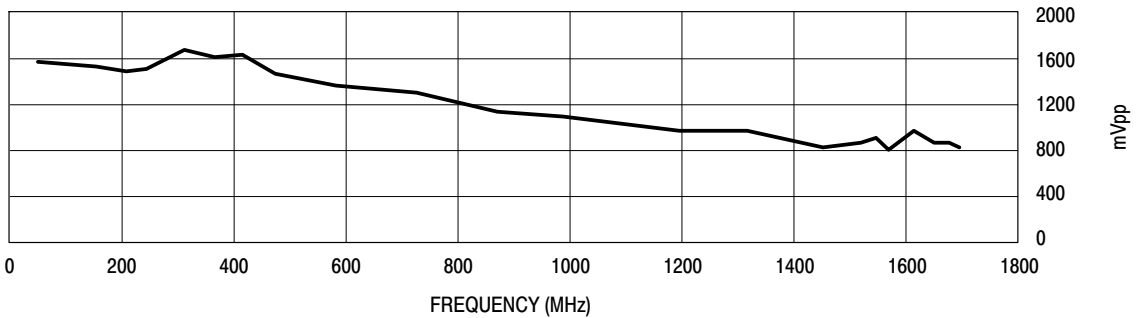
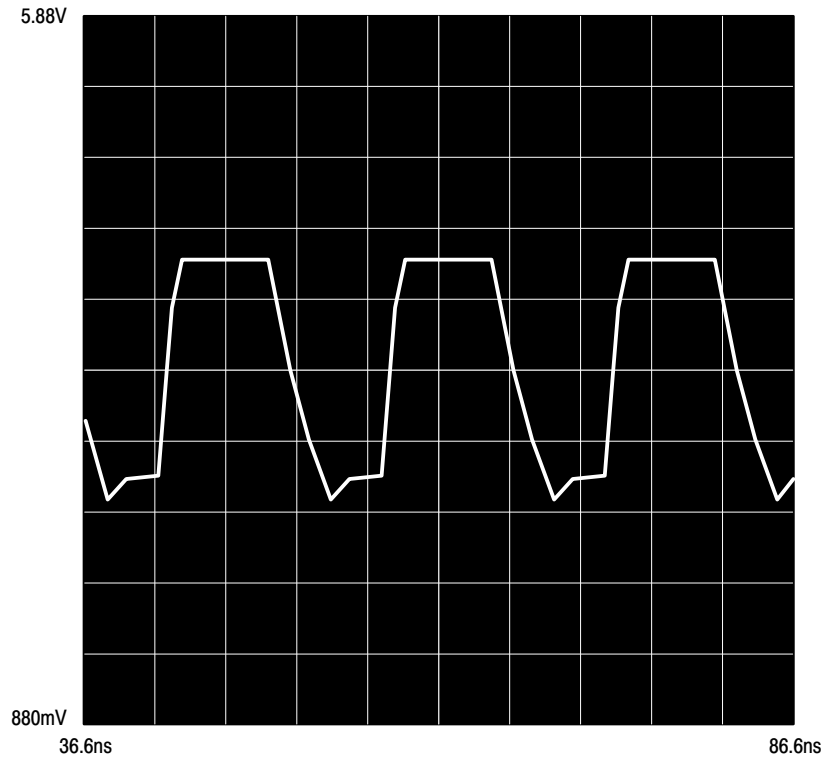


Figure 5. Output Amplitude Versus Input Frequency

MC12026A



(±8, 1.1 GHz Input Frequency, $V_{CC} = 5.0$, $T_A = 25^\circ\text{C}$, Output Loaded With 8.0pF)

Figure 6. Typical Output Waveform

MC12026A

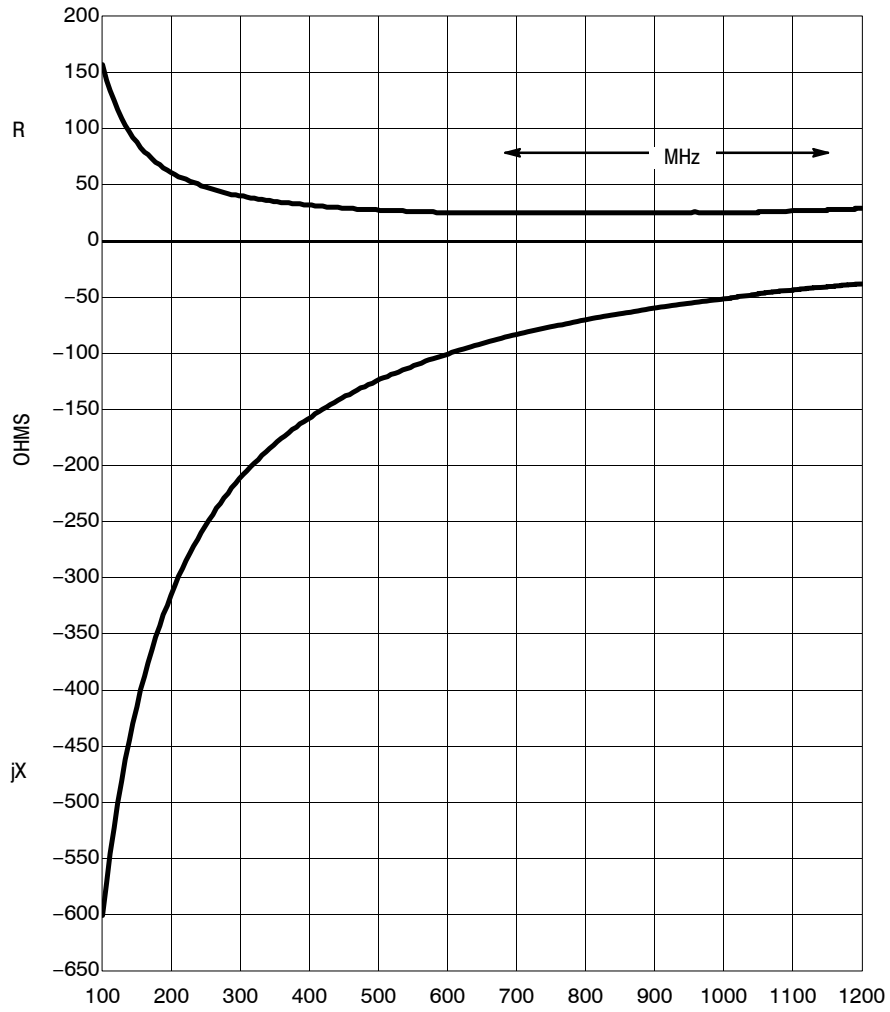
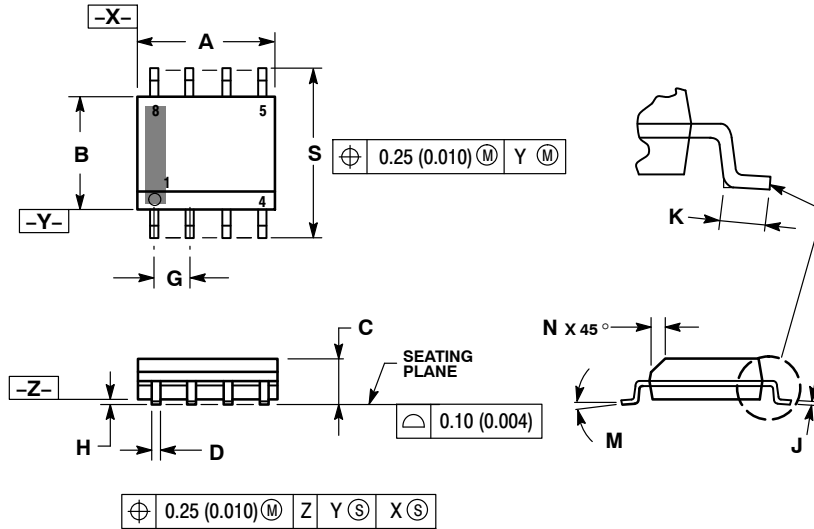


Figure 7. Typical Input Impedance Versus Input Frequency

MC12026A

PACKAGE DIMENSIONS

SOIC-8 NB
CASE 751-07
ISSUE AK

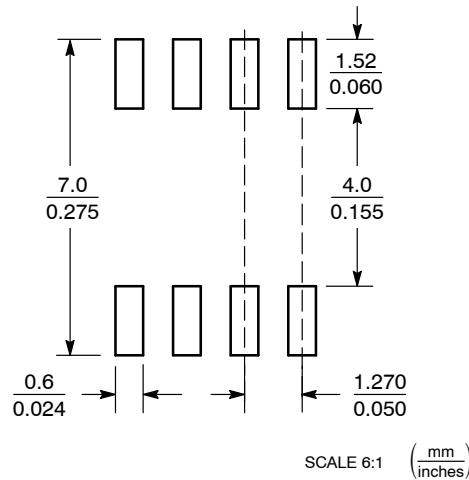


NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION A AND B DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.
6. 751-01 THRU 751-06 ARE OBSOLETE. NEW STANDARD IS 751-07.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4.80	5.00	0.189	0.197
B	3.80	4.00	0.150	0.157
C	1.35	1.75	0.053	0.069
D	0.33	0.51	0.013	0.020
G	1.27 BSC		0.050 BSC	
H	0.10	0.25	0.004	0.010
J	0.19	0.25	0.007	0.010
K	0.40	1.27	0.016	0.050
M	0°	8°	0°	8°
N	0.25	0.50	0.010	0.020
S	5.80	6.20	0.228	0.244

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, [SOLDDERM/D](#).

ECLinPS is a registered trademark of Semiconductor Components Industries, LLC (SCILLC) or its subsidiaries in the United States and/or other countries.

ON Semiconductor and are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of ON Semiconductor's product/patent coverage may be accessed at www.onsemi.com/site/pdf/Patent-Marking.pdf. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using ON Semiconductor products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by ON Semiconductor. "Typical" parameters which may be provided in ON Semiconductor data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. ON Semiconductor does not convey any license under its patent rights nor the rights of others. ON Semiconductor products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use ON Semiconductor products for any such unintended or unauthorized application, Buyer shall indemnify and hold ON Semiconductor and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that ON Semiconductor was negligent regarding the design or manufacture of the part. ON Semiconductor is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:
Literature Distribution Center for ON Semiconductor
19521 E. 32nd Pkwy, Aurora, Colorado 80011 USA
Phone: 303-675-2175 or 800-344-3860 Toll Free USA/Canada
Fax: 303-675-2176 or 800-344-3867 Toll Free USA/Canada
Email: orderlit@onsemi.com

N. American Technical Support: 800-282-9855 Toll Free
USA/Canada
Europe, Middle East and Africa Technical Support:
Phone: 421 33 790 2910
Japan Customer Focus Center
Phone: 81-3-5817-1050

ON Semiconductor Website: www.onsemi.com
Order Literature: <http://www.onsemi.com/orderlit>
For additional information, please contact your local Sales Representative